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**DEVICE AND METHOD FOR RESHAPING THE INTERCONNECTION  
ELEMENTS OF AN ELECTRONIC MODULE USING THE STRESS  
REFLOW METHOD AND, IN PARTICULAR, FOR RESTORING THE  
FLATNESS THEREOF**

ABSTRACT OF THE DISCLOSURE

A method and device are provided to reshape a set of conducting elements which are distributed over the inner face of an electronic module, said set of conducting elements forming means of positioning the module on a motherboard and/or electromagnetic armour means for the inner face of the module and/or means providing an electrical interconnection with the motherboard. The method comprises a reflow step whereby the module is subjected to the stress reflow method in a volume comprising walls having pre-determined shapes in order to enable destressing between at least some of the constituent elements of the module, such that the tips of the free ends of the set of conducting elements conform to the shape of a pre-determined two-dimensional or three-dimensional case. In one particular embodiment, the volume comprising the walls having pre-determined shapes is a volume in which a first wall, which is intended to be in contact with the tips of the free ends of the set of conducting elements, is a plane wall. In this case, the pre-determined two-dimensional or three-dimensional case is a plane and the reshaping consists in restoring the flatness thereof.